

Trade Name:

LFM-48W GT

1. Şirket adresi	Almit GmbH Unterer Hammer 3 Deutschland (D) 64720 Michelstadt - bei Frankfurt	Tel.: +49 6061 Fax: +49 6061	96925-0 96925-18

2. Validity	This specification is specified for:
	Solder Paste Lead Free LFM-48W GT
	Delivered by Almit GmbH to:

3. Diameter & Allowence

Weight	20g	40g	80g	100g	250g
Allowance			-0, +5	g	

4. Deliverable Reel Size

Metal Name	Solidus °C	Liquidus °C	Specific Gravity
LFM-48	217	220	7.4

5. Physical Properties

Test	Characteristics	Test Methods
Metal Content	88.0 ± 1.0	IPC-TM-650 2.2.20
Silver Chromate	pass	IPC-TM-650 2.3.33
Copper Mirror Test	pass	IPC-TM-650 2.3.32
SIR (85°C, 85%, 168hr) (Ω)	$\geq 1 \times 10^8$	IPC-TM-650:2.6.3.3
Corrosion Test	pass	IPC-TM-650 2.6.15
Flux materials composition	RO	J-STD-004 1.2
Quantitative Halide	L1 < 0.5%	IPC-TM-650 2.3.35
Fluorides By Spot Test	pass	IPC-TM-650 2.6.35.1

6. Characteristics

Composition				Compo	nents			
Composition	Sn	Ag	Cu	Pb	Sb	Bi	Au	In
Standard	Rest	3.0	0.5	<0.05	≤0.10	≤0.05	≤0.05	≤0.10
Composition	Components							
Composition	Al	As	Cd	Fe	Ni	Zn		
Standard	≤0.001	≤0.03	≤0.002	≤0.02	≤0.01	≤0.001		

7. Solder Powder Size & Distribution

Туре	larger than	less than 1%	at least 80%	at most 10%
Type 4 V16L	40 Microns	38 Microns	20 - 38 Microns	20 Microns

A single lot is consisted of, and may vary between 10 - 100kg, depends upon the production plan.

9. Quality and Inspection

Inspection items are applied to each lot as follows:

Test No.	Inspection Item	Contents			Standard
1	Appearance	Color Comparison with Limit Specimen		h Limit Specimen	
2	Weight		•		
3	Solder Powder Size	20-38 μm	94	≤	(wt%)
		Sn	Re	est	(wt%)
4 Metal Composition	Ag	3.0 =	± 0.2	(wt%)	
	Cu	0.5 ± 0.1		(wt%)	
		Solder Balling Test	Comparison with Limit Specimen		
5 Characteristics		Viscosity (Spiral type, 10rpm, 25°C) (IPC-650-2.4.34.3)	$\begin{array}{c c} 190000 \pm 30000 \ 190 \\ \pm \ 30 \end{array} (cps) \ (Pa.s)$		(cps) (Pa.s)
	Solderability on Cu- Plate	Comparison with Limit Specimen		h Limit Specimen	
		Dryness	Chalk powder should be easily removed from each test specimen.		

*Straight lines of solder paste are printed on a JIS-2 type substrate then reflowed. The reflowed solder is examined with a stereo microscope at 30X magnification. No more than 2 solder balls larger than one fifth the size of the pattern gap is allowed per gap.

10. Packing

Indiv	vidual Package	Ou	ter Package
Unit	Packing	Unit	Packing
20g	5cc Cartridge		
40g	10cc Cartridge		
80g	30cc Cartridge		Cardboard box
100g	30cc Cartridge		
250g	100cc Cartridge		

11. Identification

	Polyethylene bottle	Cardboard
Name	LFM-48W GT	same as the left
Lot Nr.	(Ex) 120119-9	dto.
Solder Powder Size	V16L	dto.
Date of Mfg.	(Ex.) 19.01.2012	dto
Net-Weight	(Ex.) 500g	dto.
Maker	Nihon Almit Co. Ltd.	dto.

12. Maker Address

Nihon Almit Co. Ltd. Almit Bldg., 2-14-2 Yayoicho, Nakano-ku, Tokyo, Japan

13. In case of changing this specification it should be accepted by Signature_____ Date_____

14. This product is manufactured, using all guaranteed materials according to the legal law regulations

15. Shelf Life

- 1. Refrigerating is recommended at a temperature of 2-8°C to guarantee shelf life of 7 months
- 2. Paste can be stored at room temperature for 1 week up to 25°C prior to use (only applicable for jars)